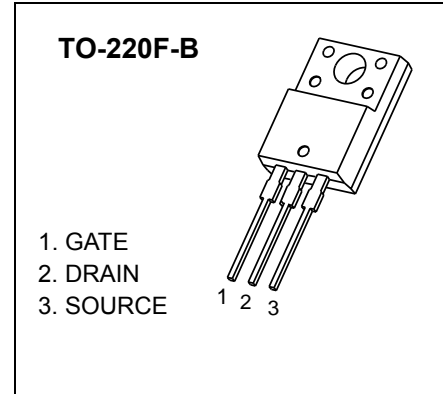




TO-220F-B Plastic-Encapsulate MOSFETS

PF07N65M1 N-Channel Power MOSFET

| | | |
|---------------|-----------------|-------|
| $V_{(BR)DSS}$ | $R_{DS(on)HMD}$ | I_D |
| 650V | 1.0Ω@10V | 7A |



GENERAL DESCRIPTION

This advanced high voltage MOSFET is designed to stand high energy in the avalanche mode and switch efficiently. This new high energy device also offers a drain-to-source diode fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits.

FEATURES

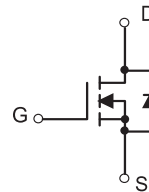
- High Current Rating
- Lower $R_{DS(on)}$
- Lower Capacitance
- Lower Total Gate Charge
- Tighter V_{SD} Specifications
- Avalanche Energy Specified
- Fast Switching Capability

MARKING



07N65M1 = Device code.
 Solid dot = Green molding compound device,
 if none, the normal device.
 XXXX = Code.

EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|--------------------------------------------------|-------------------|----------|------|
| Drain-Source Voltage | V_{DS} | 650 | V |
| Gate-Source Voltage | V_{GS} | ±30 | V |
| Continuous Drain Current | I_D ① | 7 | A |
| Pulsed Drain Current | I_{DM} ② | 28 | A |
| Single Pulsed Avalanche Energy | E_{AS} ③ | 223 | mJ |
| Maximum Power Dissipation | P_D ① | 50 | W |
| Thermal Resistance from Junction to Ambient | $R_{\theta JA}$ | 62.5 | °C/W |
| Thermal Resistance from Junction to Case | $R_{\theta JC}$ ① | 2.5 | °C/W |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55~+150 | °C |

MOSFET ELECTRICAL CHARACTERISTICS

$T_J=25\text{ }^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------------------------------------------|-----------------------|--------------------------------------------------------|-----|------|-----------|----------|
| Off characteristics | | | | | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 650 | | | V |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 520V, T_J = 25^\circ C$ | | | 1.0 | μA |
| | | $V_{GS} = 0V, T_J = 125^\circ C$ | | | 100 | |
| Gate-body leakage current | I_{GSS} | $V_{DS} = 0V, V_{GS} = \pm 30V$ | | | ± 100 | nA |
| On characteristics ^④ | | | | | | |
| Gate-threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2.0 | 3.1 | 4.0 | V |
| Static drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 3.5A$ | | 1.0 | 1.2 | Ω |
| Dynamic characteristics ^⑤ | | | | | | |
| Input capacitance | C_{iss} | $V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$ | | 1060 | | μF |
| Output capacitance | C_{oss} | | | 99 | | |
| Reverse transfer capacitance | C_{rss} | | | 8 | | |
| Gate resistance | R_g | $f = 1MHz$ | | 4 | | Ω |
| Switching characteristics ^⑤ | | | | | | |
| Total gate charge | Q_g | $V_{GS} = 10V, V_{DS} = 520V, I_D = 7A$ | | 25 | | nC |
| Gate-source charge | Q_{gs} | | | 5 | | |
| Gate-drain charge | Q_{gd} | | | 10 | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 60V, V_{GS} = 10V, R_G = 25\Omega, I_D = 7A$ | | 19 | | ns |
| Turn-on rise time | t_r | | | 61 | | |
| Turn-off delay time | $t_{d(off)}$ | | | 69 | | |
| Turn-off fall time | t_f | | | 27 | | |
| Drain-Source Diode Characteristics | | | | | | |
| Drain-source diode forward voltage | V_{SD} ^④ | $V_{GS} = 0V, I_S = 7A$ | | | 0.9 | V |
| Continuous drain-source diode forward current | I_S ^① | | | | 7 | A |
| Pulsed drain-source diode forward current | I_{SM} ^② | | | | 28 | A |

Notes:

- $T_C = 25^\circ C$ Limited only by maximum temperature allowed.
- $P_W \leq 10\mu s$, Duty cycle $\leq 1\%$.
- EAS condition: $V_{DD} = 50V, V_{GS} = 10V, L = 10mH, R_g = 25\Omega$ Starting $T_J = 25^\circ C$.
- Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production.